

Nanoimprint Lithography and Applications at Hewlett Packard Labs

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Outline



- Background
- Motivation
- Nanoimprint lithography at HP labs
- Applications based on nanofabrication
 - Molecular memory and logic
 - Nanowire biological sensor
 - Nano-enhanced spectroscopy (unpublished)
- Future work
- Summary

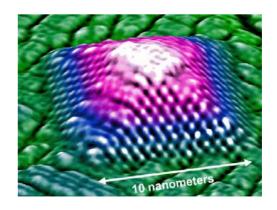


Quantum Science Research



- Part of Advanced studies, HP labs
- Duty: Exploring "the next big thing" for HP
- Built and directed by Dr. R. Stan Williams, HP Senior Fellow
- •30 people







Nano is Great but...

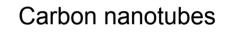


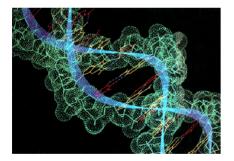
New frontier of science

- o Fundamental knowledge
- o Convergence of physics, chemistry and biology.

Potential commercial impact

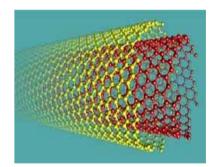
DNA







Molecular electronics



Technological challenge – Lithography!



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Extreme UV lithography (EUV)

-Extremely expensive

(complex optical system, expensive and fragile mask)

X-ray lithography

-Expensive light source (synchrotron preferred)

-Mask material

E-beam direct write lithography (EBL)

-Extremely slow (serial process)

E-beam projection lithography (EPL)

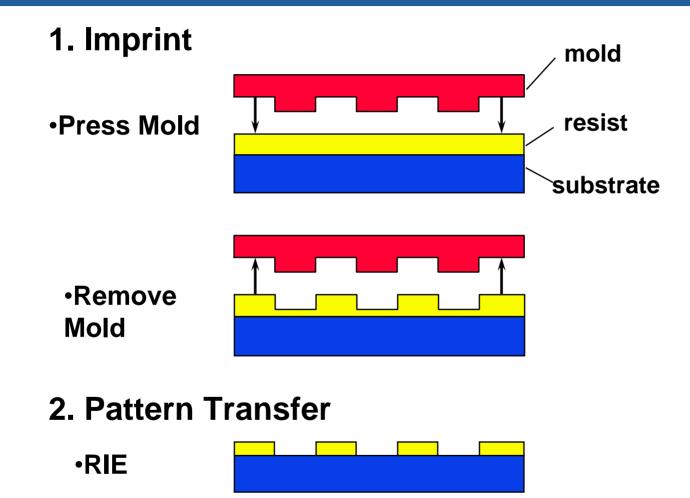
-Mask material

-Distortion due to heat



Nanoimprint Lithography (NIL)





Chou, Krauss, and Renstrom, APL, Vol. 67, 3114 (1995); Science, Vol. 272, 85 (1996)

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Nanoimprint Lithography (NIL)

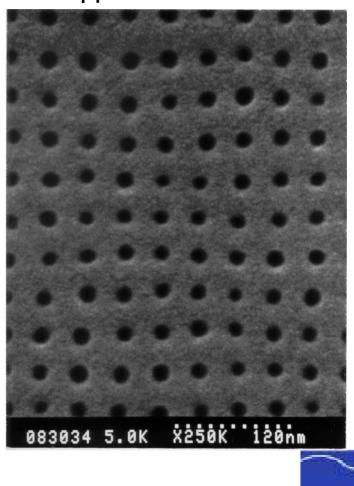


•High resolution -not limited by wavelength

•High throughput -parallel process

Low cost

→||← 10 nm

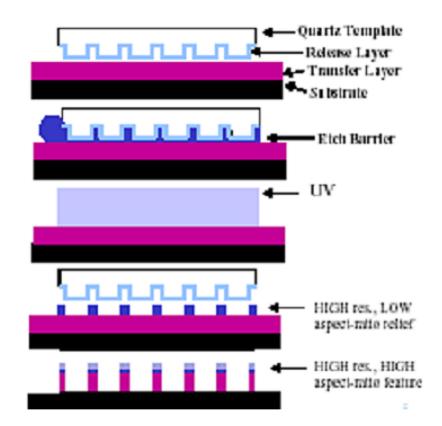


Chou, Krauss, and Renstrom, APL, Vol. 67, 3114 (1995); Science, Vol. 272, 85 (1996)

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Step & Flash Imprint





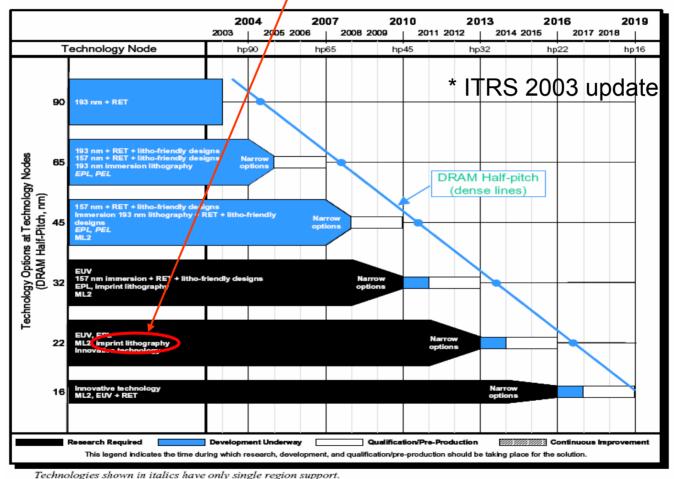
- •UV curable process
- •Room temperature
- •Low pressure
- •UV polymer is applied by droping

M. Colburn, A. Grot, G. Wilson's et al SPIE 2000



NIL is on ITRS (international technology) roadmap for semiconductors)

We helped to put NIL on ITRS



RET—resolution enhancement technology EUV—extreme ultraviolet EF ML2—maskless lithography PEL—proximity electron lithography

EPL-electron projection lithography



Major Players



Princeton University

University of Taxes at Austin

University of Michigan

Hewlett-Packard

Motorola

Micro resist...

Europe:

Aachen University. Lund University...

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Obducat, EVG, SUSS...
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Japan:

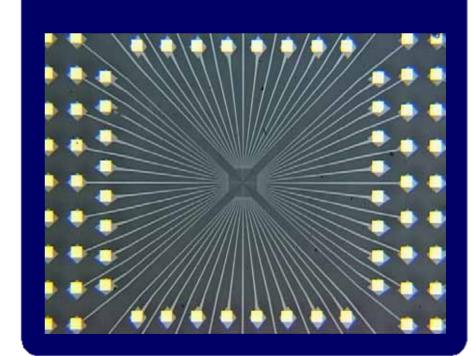
Hitachi...

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- ---- Nanonex
- ---- Molecular Imprints



Crossbar Molecular Electronics by NIL





What is Next?

ENIAC - circa 1947



Shrink by 10⁸

Improve power efficiency by 10⁸

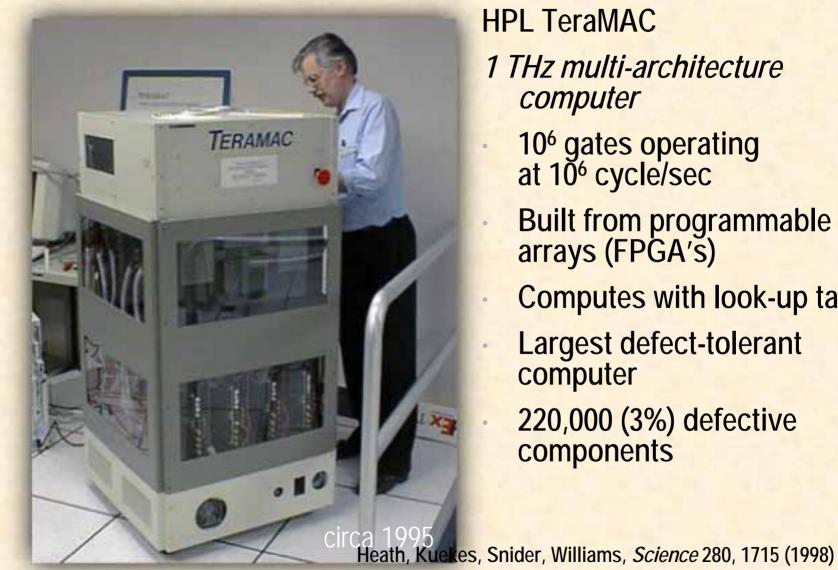
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HP Pocket PC

An Architecture for Molecular Molectronics





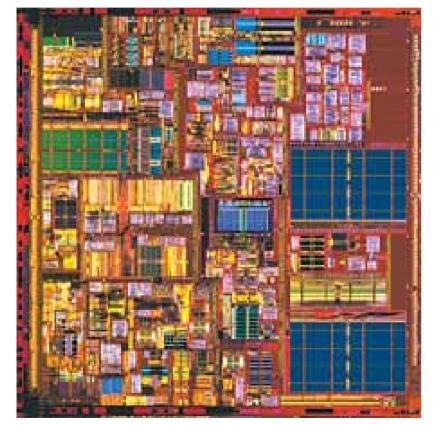
HPL TeraMAC

- 1 THz multi-architecture computer
 - 10⁶ gates operating at 10⁶ cycle/sec
 - Built from programmable gate arrays (FPGA's)
 - **Computes with look-up tables**
 - Largest defect-tolerant computer
 - 220,000 (3%) defective components

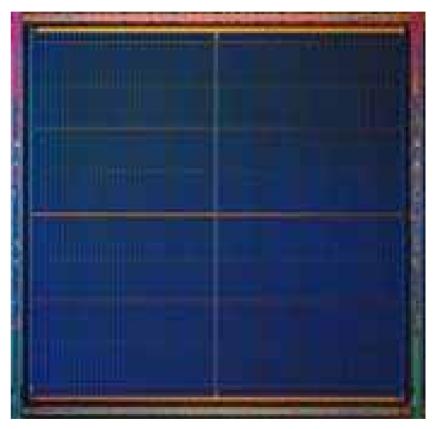


An Architecture for Molecular Electronics





A microprocessor (intel P4)

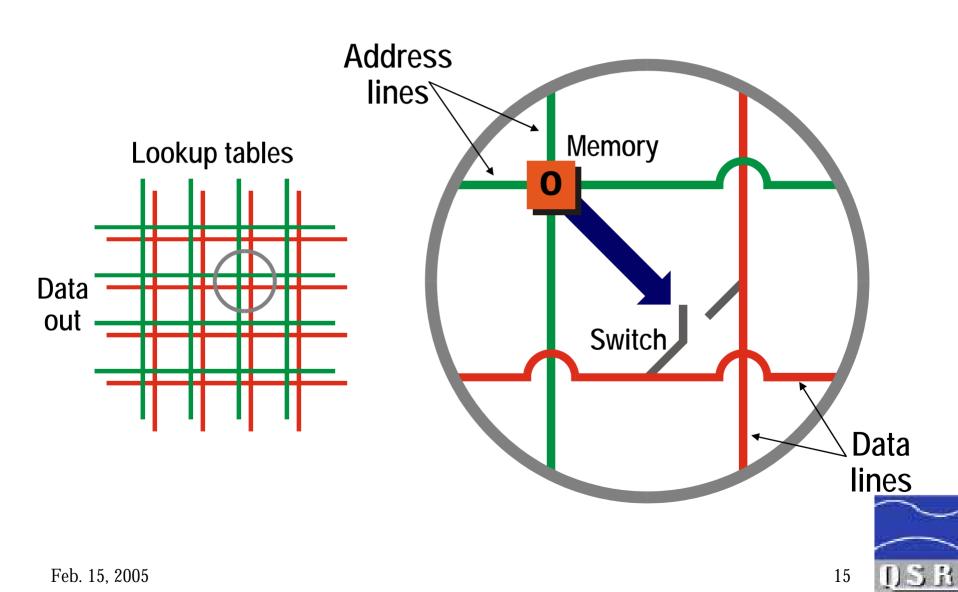


A reconfigurable device (FPGA)



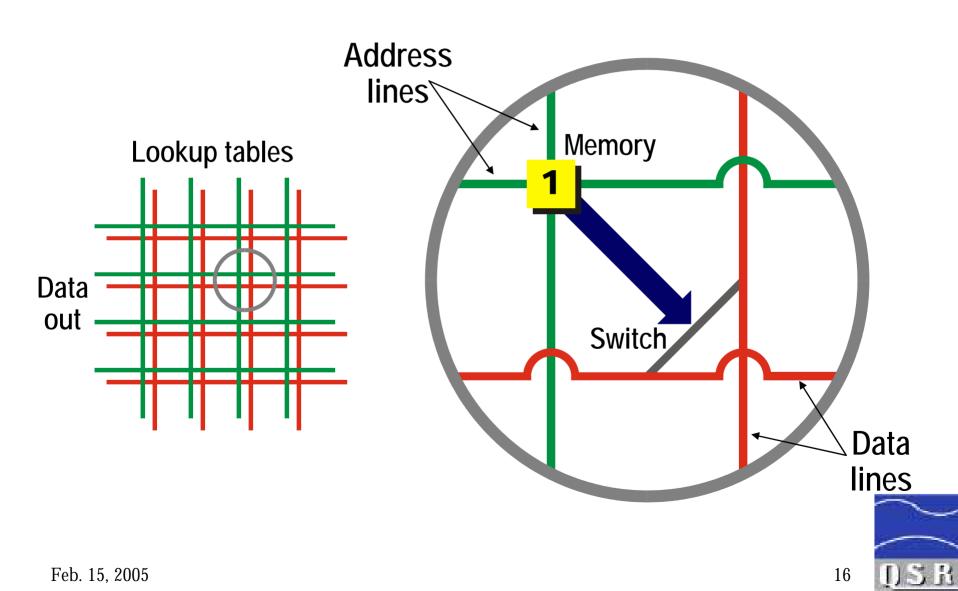
Teramac Crossbar Architecture





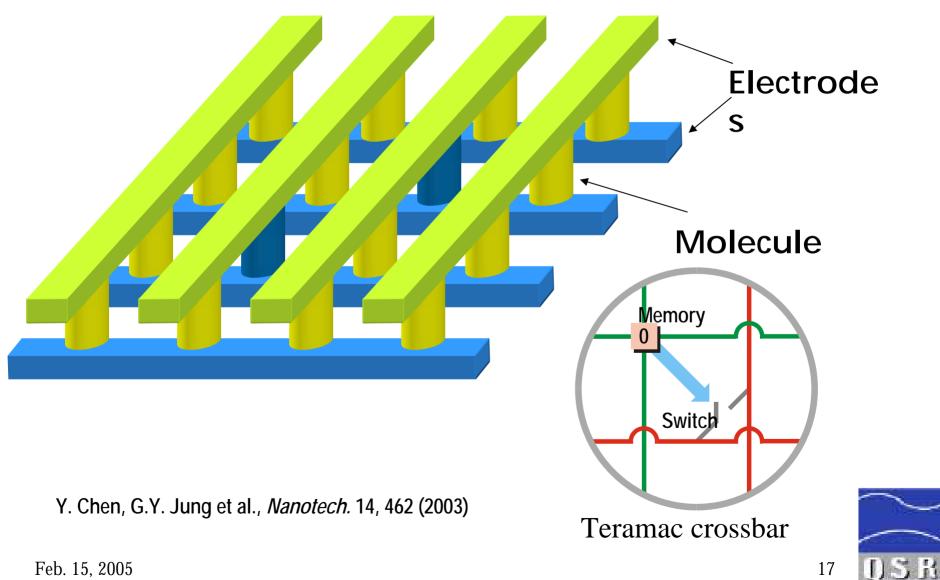
Teramac Crossbar Architecture





Nano-circuit Crossbar Architecture

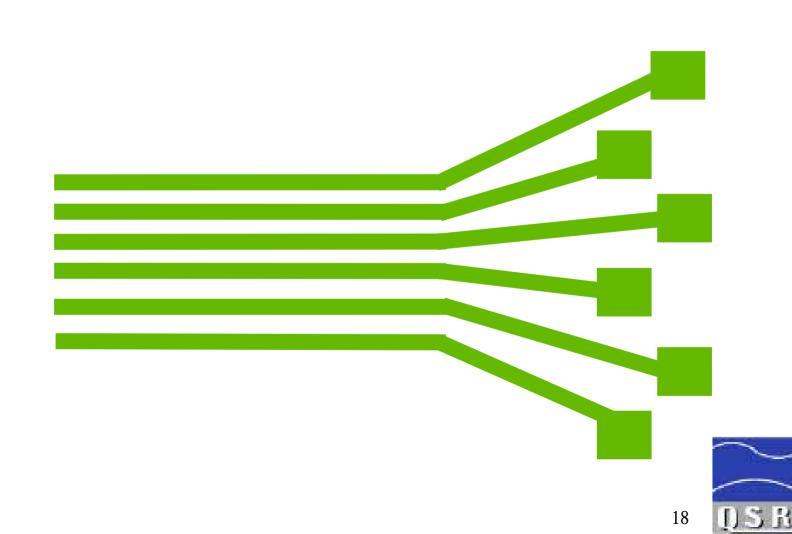




Crossbar Fabrication: Bottom Electrode

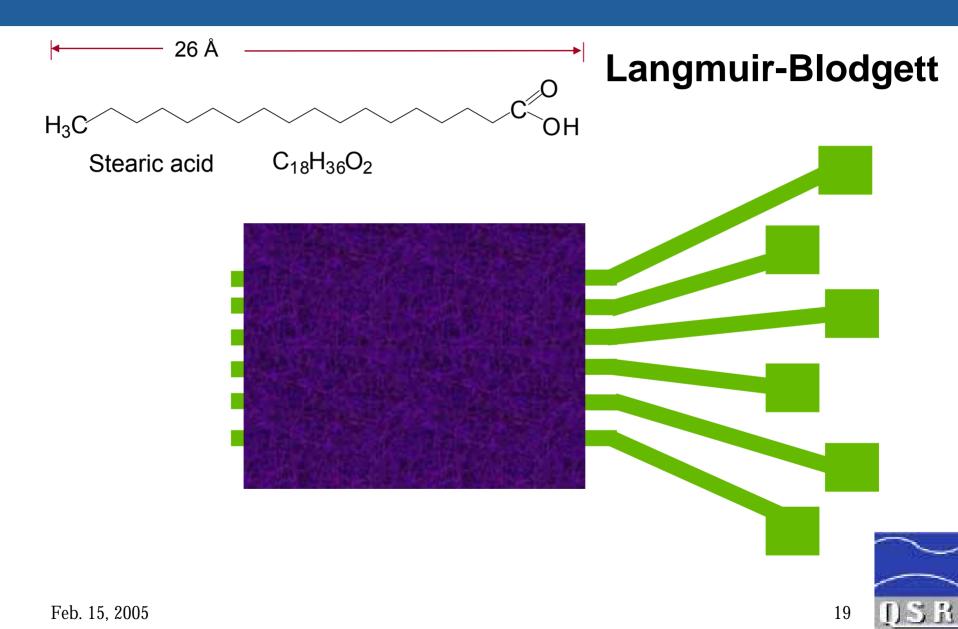


Nanoimprint



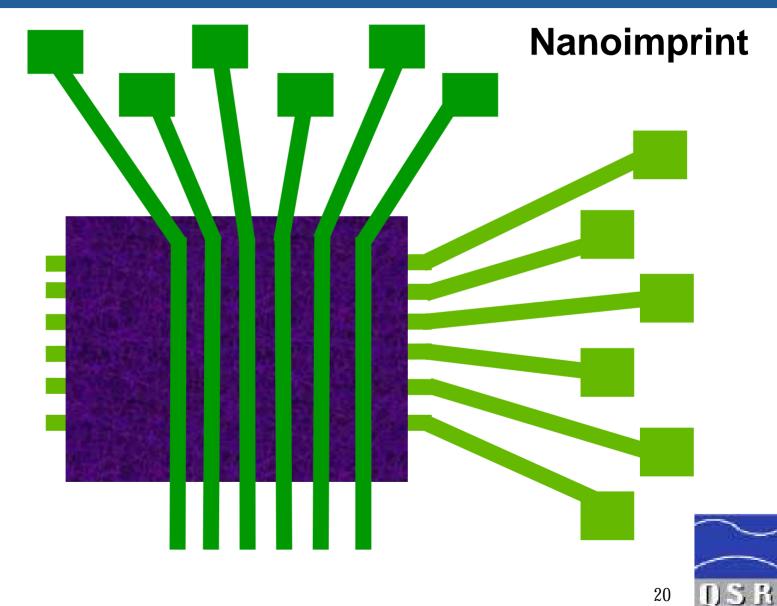
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Crossbar Fabrication: Molecule Deposition



Crossbar Fabrication: Top Electrode

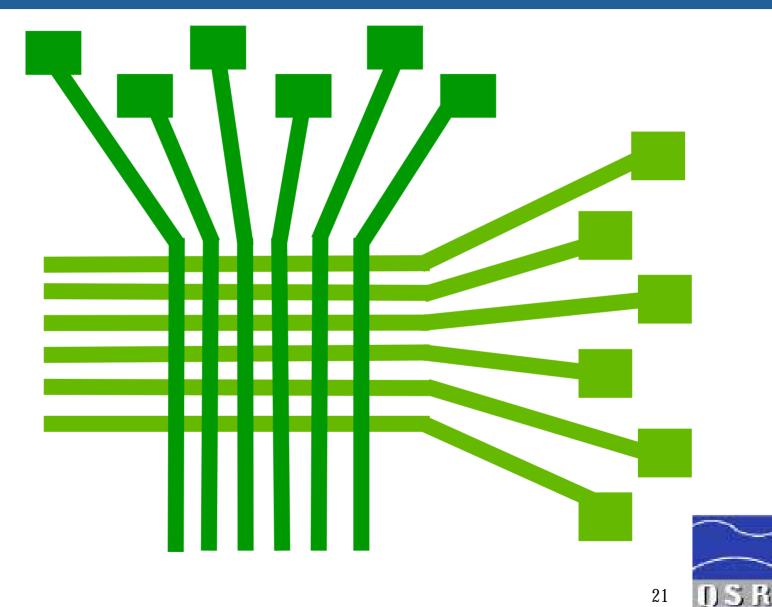




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Crossbar Fabrication: Etch Back

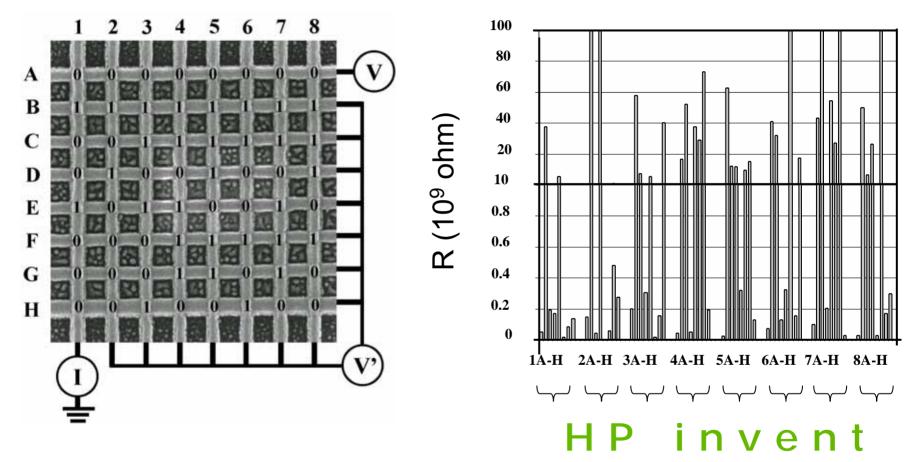




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64 bits Cross-bar Memory at 60 nm Half-pitch by Thermal Nanoimprint Lithography





- •First working circuit fabricated using NIL
- •First working Molecular memory circuit

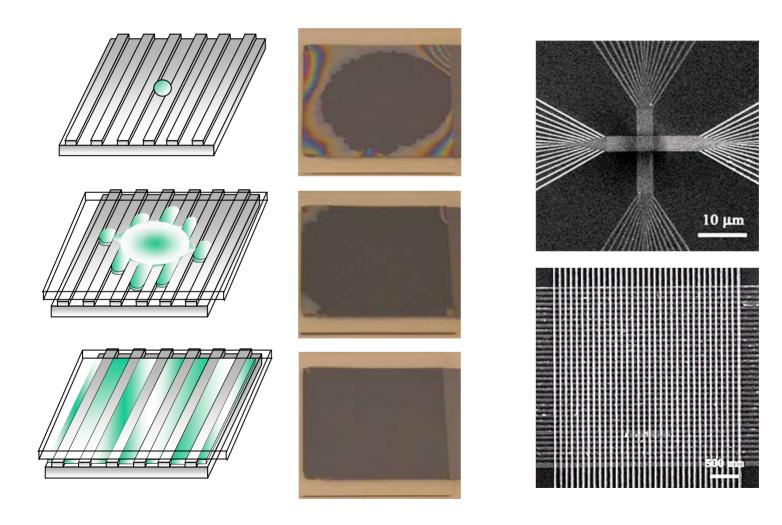
Y. Chen, G.Y. Jung et al., Nanotech. 14, 462 (2003)

Feb. 15, 2005



34X34 Cross-bar Structure at 50 nm Half-pitch by UV-curable NIL with Dropping Resist





G.Y. Jung, S. Ganapathiappan et al. Nano Letter 4 (2004),

Feb. 15, 2005

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SR



Challenges:

• Resist stick to the mold

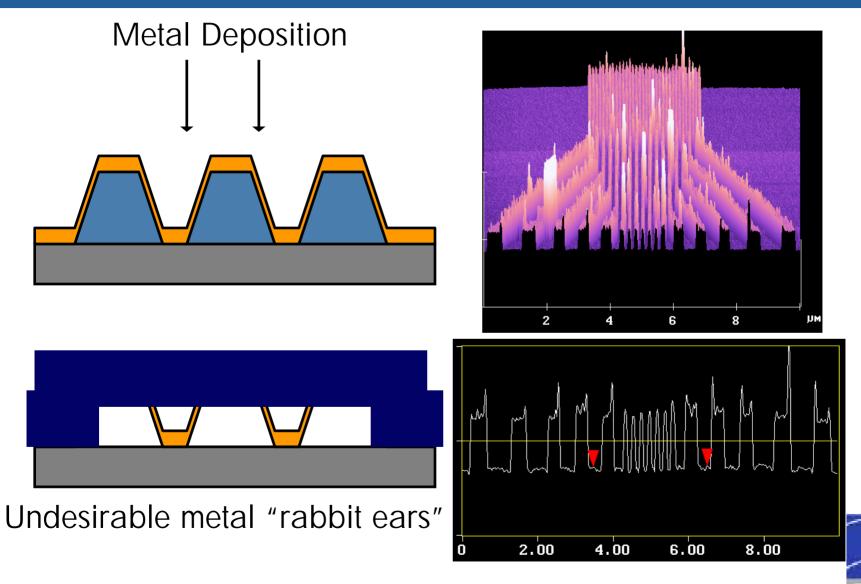
Mechanical properties and lift-off properties have to be comprimised

• "Rabbit ears" problem



"Rabbit ears" Problem





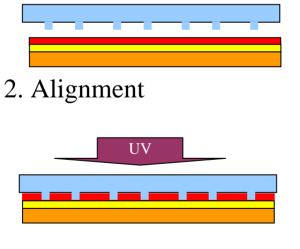
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UV-curable NIL with Double-layer Spin-on Resist



 Prepare substrate, **spin** under layer and resist (Nanonex NXR 2010) on



3. Press and exposure

4. Mold and substrate separation



5. Residue layer and under layer etching



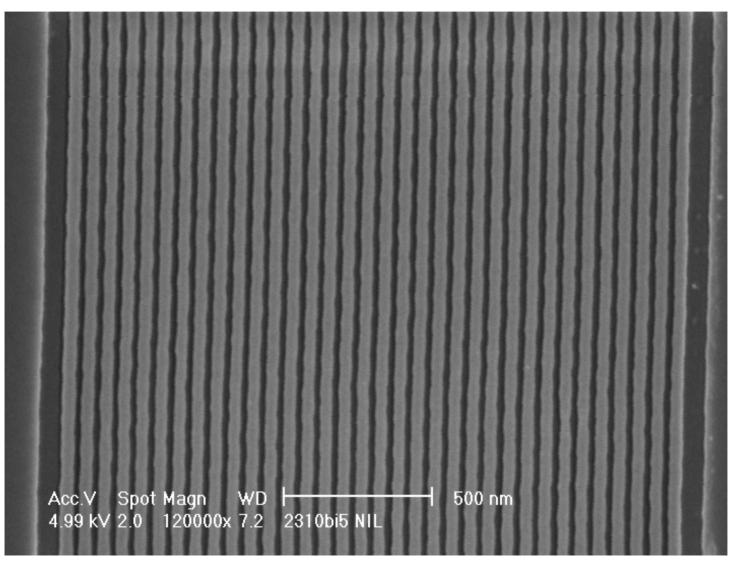
6. Metal evaporation and lift-off

W. Wu, H. Ge, S.Y. Chou et al., EIPBN 2004



Imprinted 30 nm Half-pitch Nanowires on NIL Resist





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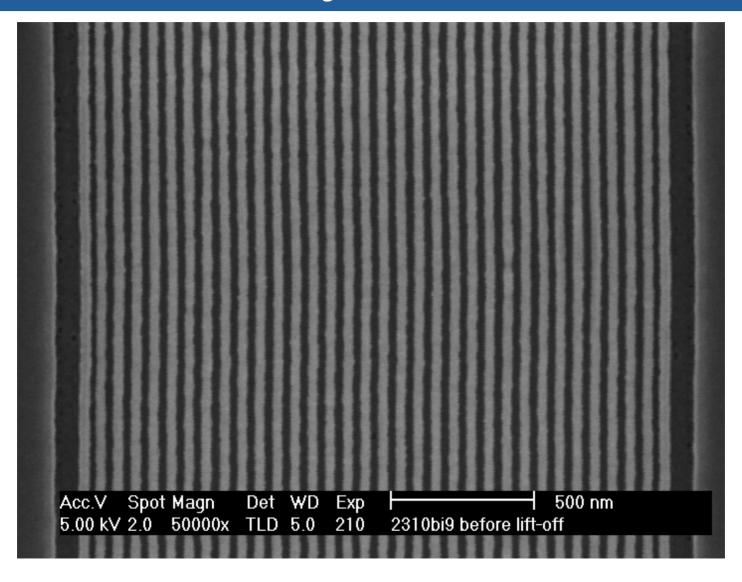
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

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Imprinted 30 nm Half-pitch Nanowires Etched into Under-layer





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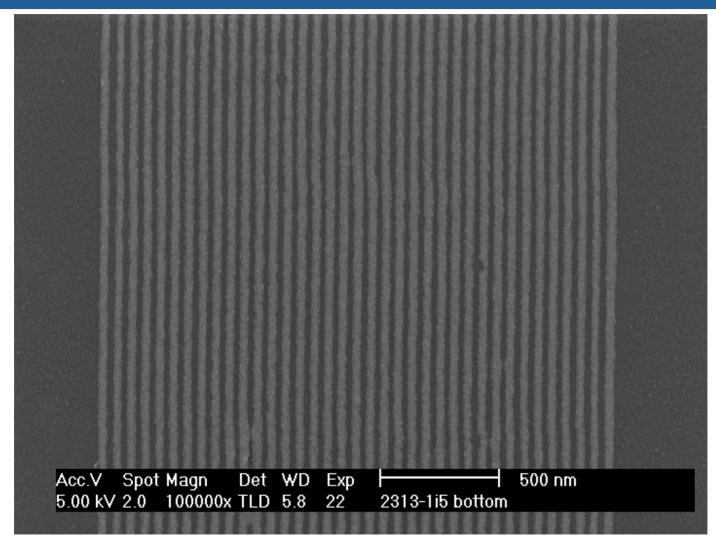
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

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Ti/Pt Nanowires at 30 nm Half-pitch Fabricated Using NIL and Lift-off





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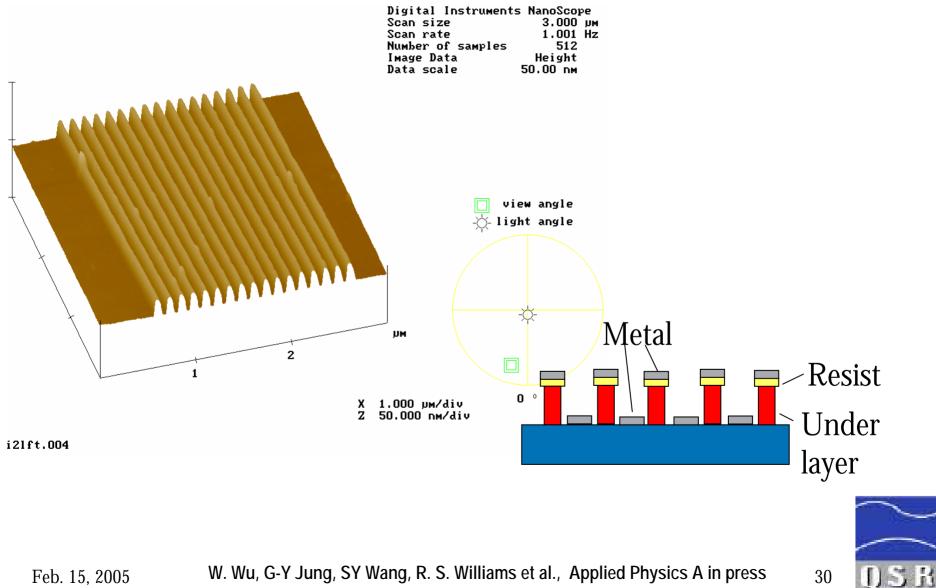
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

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SR

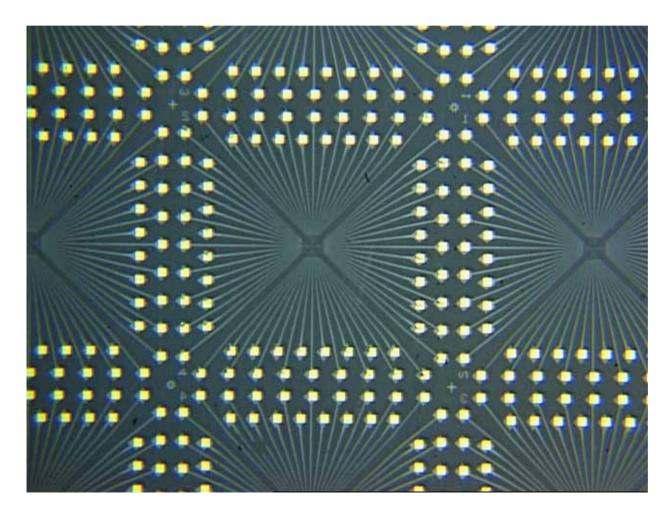
Rabbit Ears" Solved with Controlled Under-cut



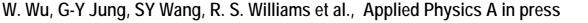


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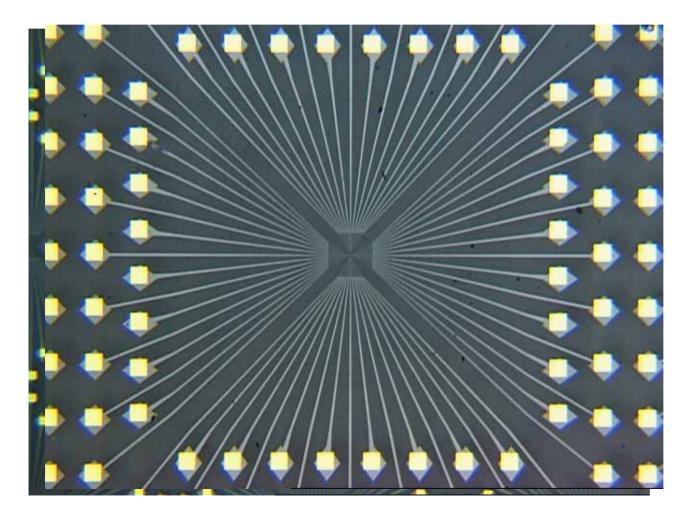
30 nm Half-pitch 34X34 Crossbar Molecular Memory Fabricated using NIL and Lift-off



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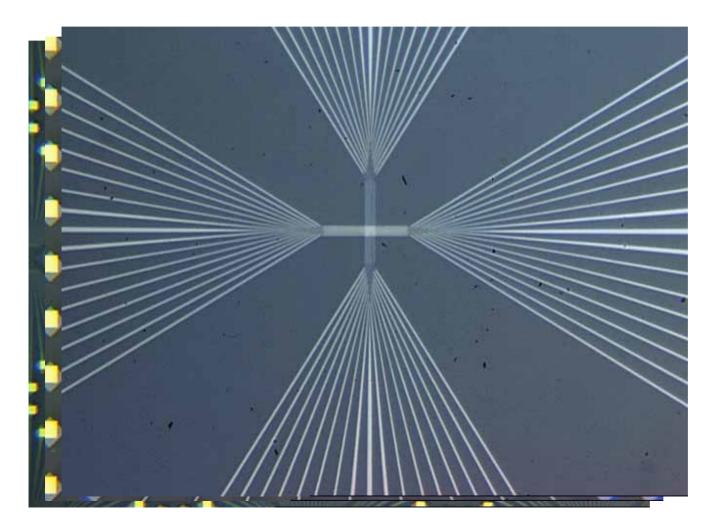




OSR

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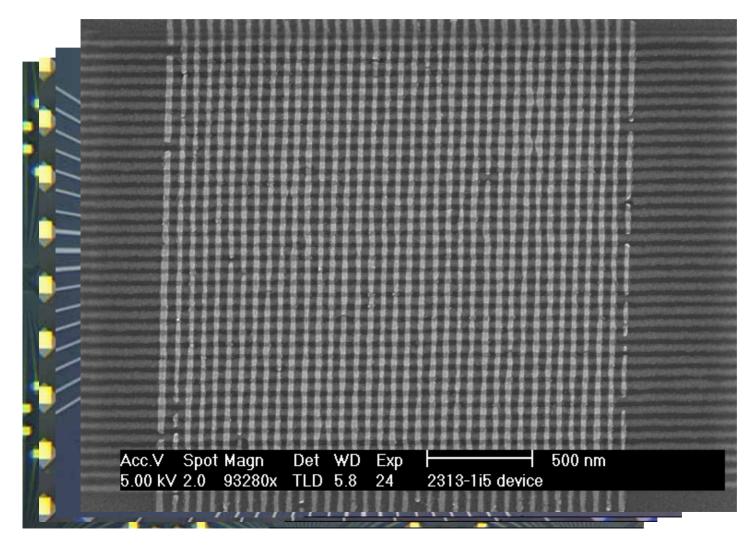
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press



0 S R

Feb. 15, 2005

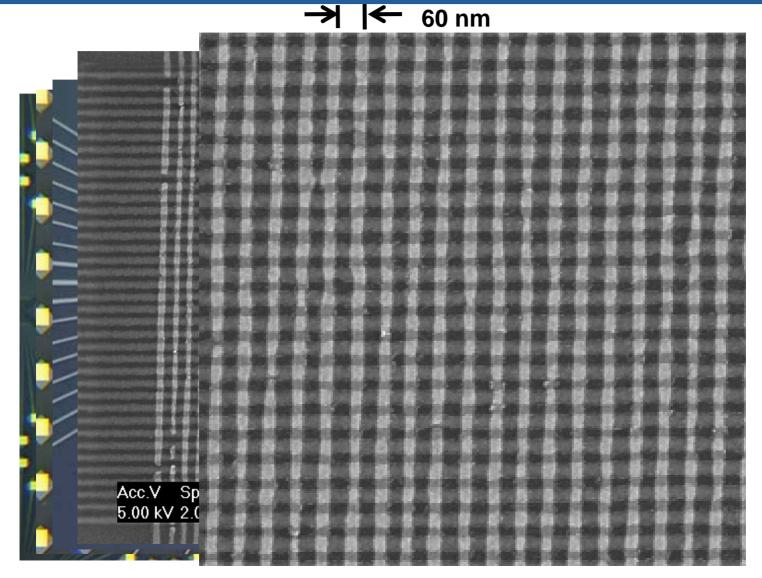
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press



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W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

OSR



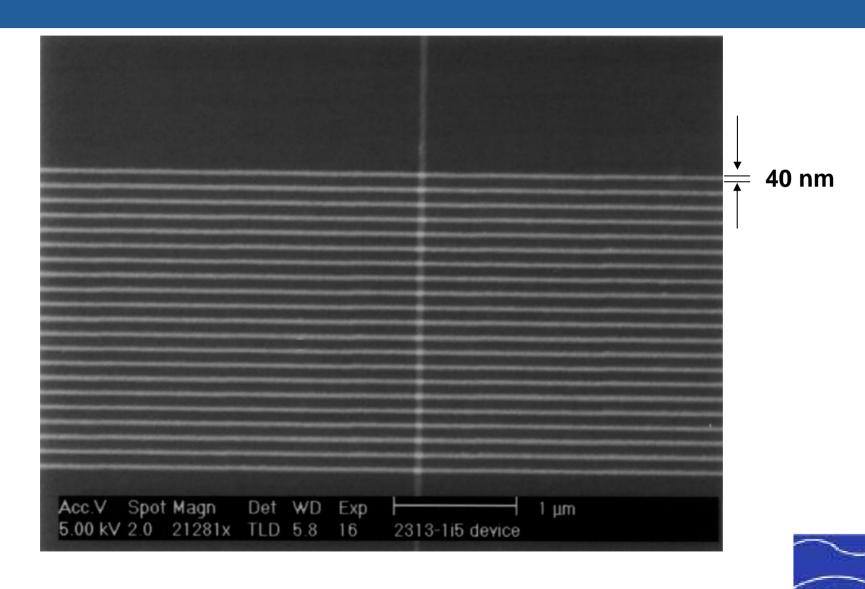
35 <u>0 S R</u>

Feb. 15, 2005

W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

1X17 Testing Devices Array





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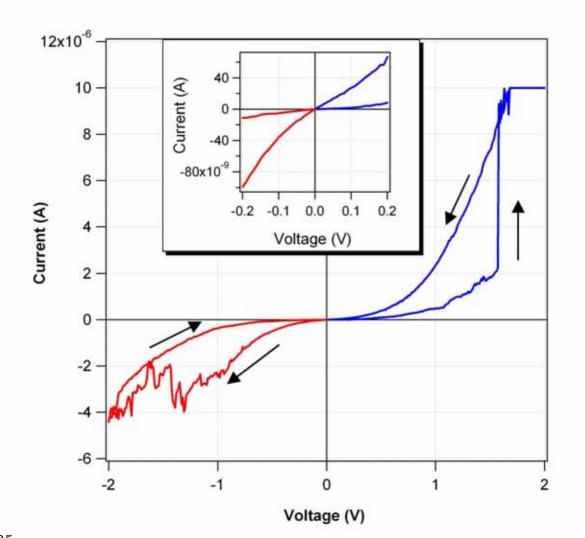
W. Wu, G-Y Jung, SY Wang, R. S. Williams et al., Applied Physics A in press

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I-V Curve of Single Device





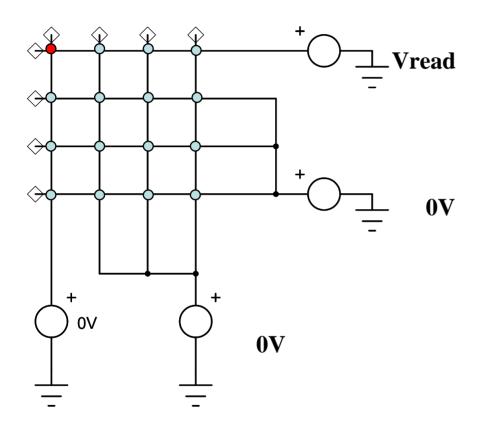
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×



Array Characterization Setup





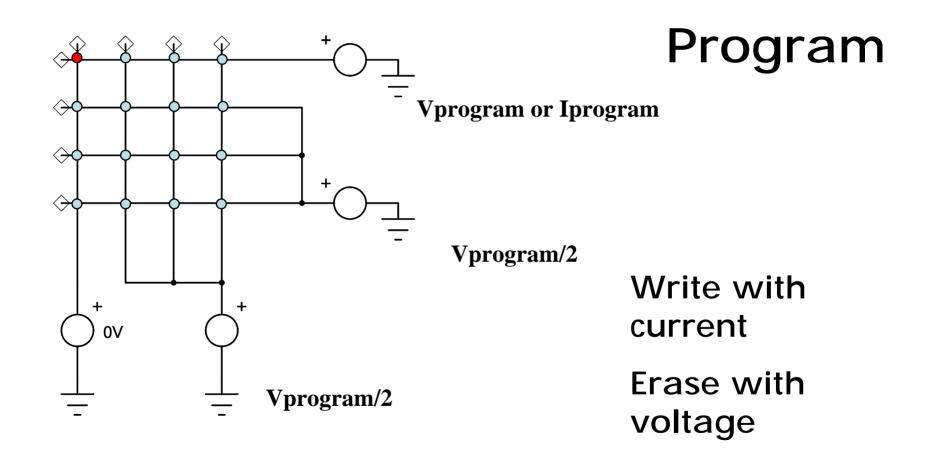
Read



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Array Characterization Setup



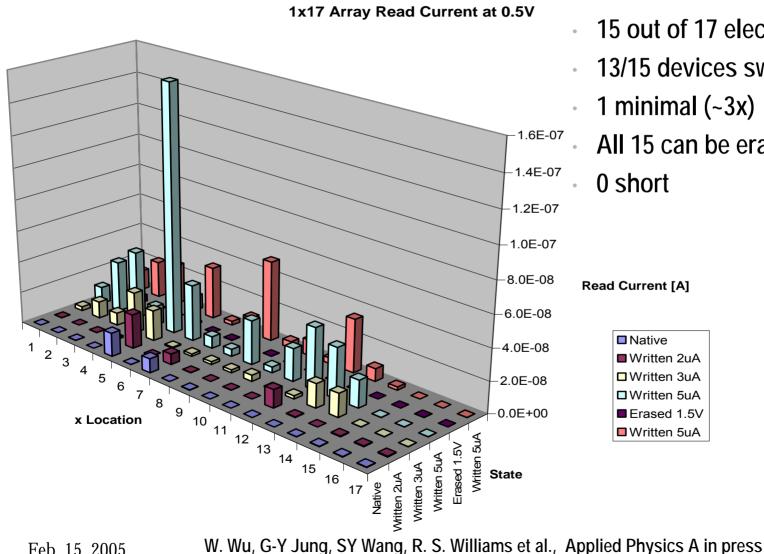




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Read, Write and Erase of 1X17 Array





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- 15 out of 17 electrodes good
- 13/15 devices switch (> 10)
- 1 minimal (~3x)
- All 15 can be erased

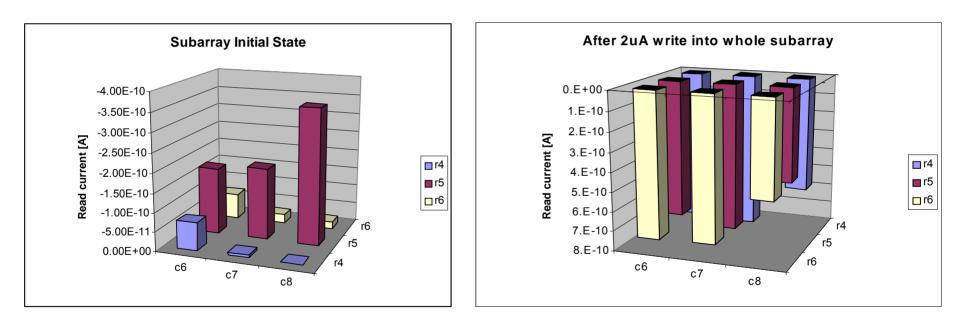
0 short





Initial state of a subarray

After writing into whole subarray

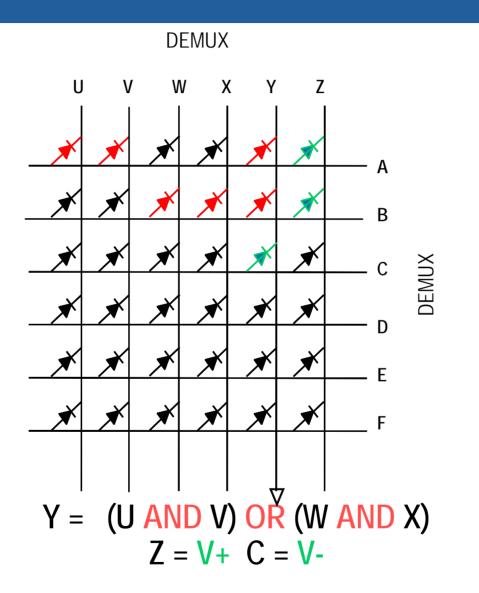




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Crosspoint diode logic array: half-adder

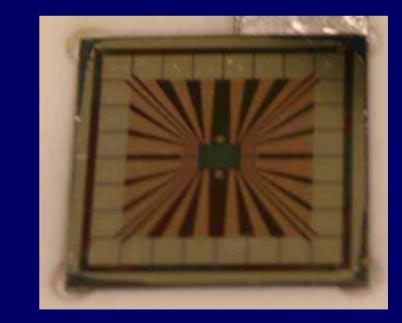






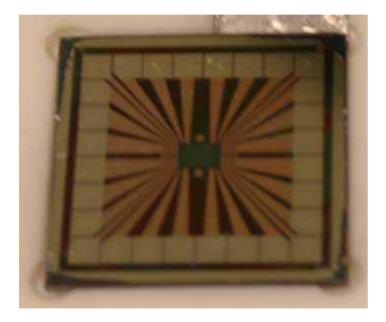
invent

Nanowire Biological Sensor



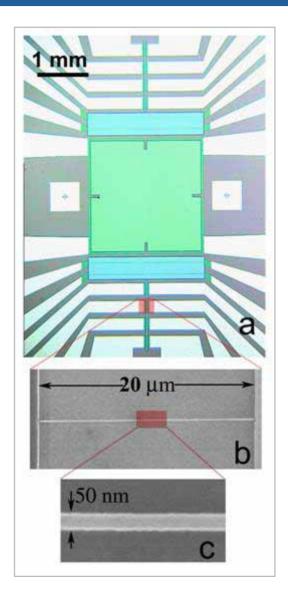
Sensor chip structure





Zhiyong Li, Yong Chen, Xuema Li, Ted Kamins, and Stan Williams

Nano Letters, 4(2004), 245

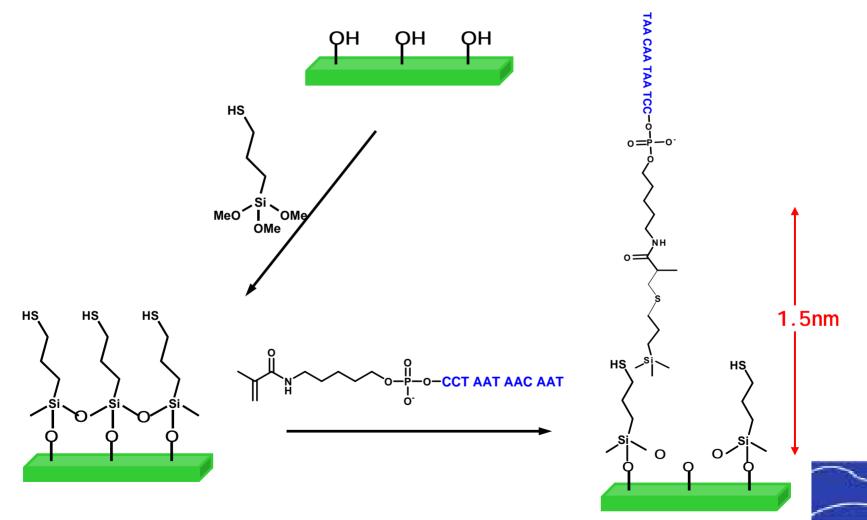




Covalent attachment of ss-DNA on SiNW



DSR

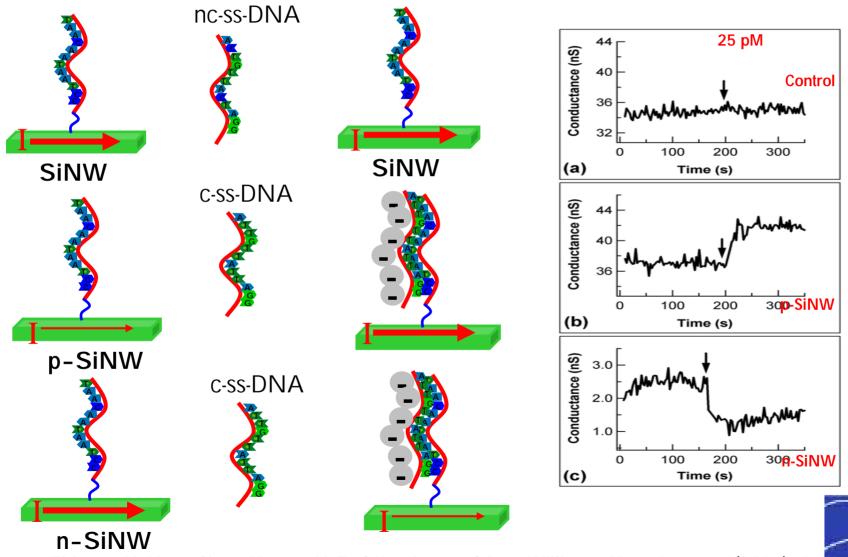


Zhiyong Li, Yong Chen, Xuema Li, Ted Kamins, and Stan Williams Nano Letters, 4(2004), 245 Feb. 15, 2005

DNA sensing



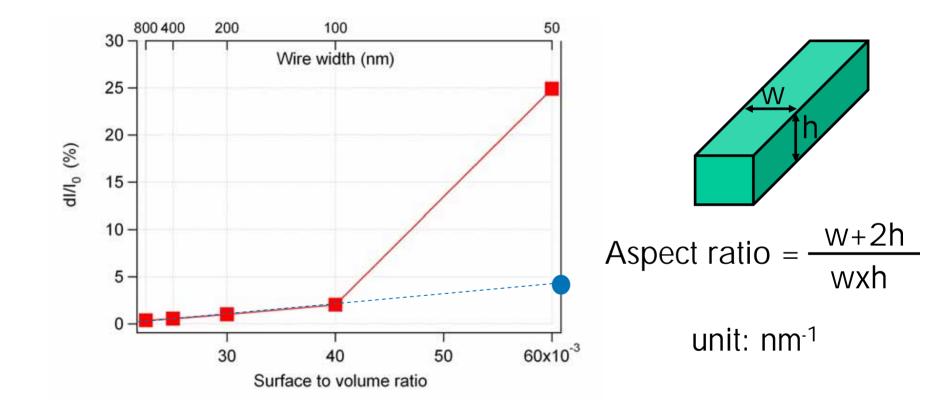
DSR



Zhiyong Li, Yong Chen, Xuema Li, Ted Kamins, and Stan Williams Nano Letters, 4(2004), 245 Feb. 15, 2005

Size matters – dI/I_0 vs aspect ratio of wires







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Z. Li, X. Li and R. S. Williams et al. Applied physics A in press

Future Work: Next Generation Nanoimprint Machine

Challenges of NIL:

- Yield (It will be improved over time.)
- Alignment accuracy is currently 10x worse than resolution -Alignment must be achieved without high cost

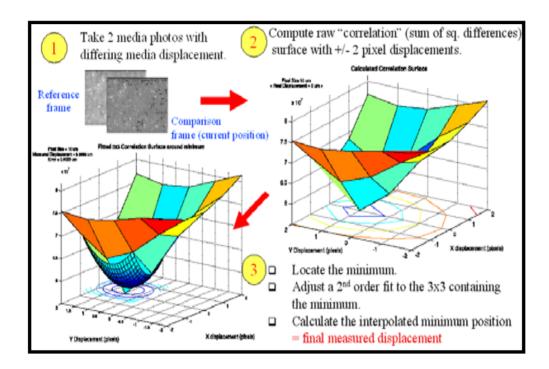
Answer:

Next generation nanoimprint machine



Nano Displacement Sensing & Estimation (NDSE) Technology (HTL/ Precision Imaging Program)





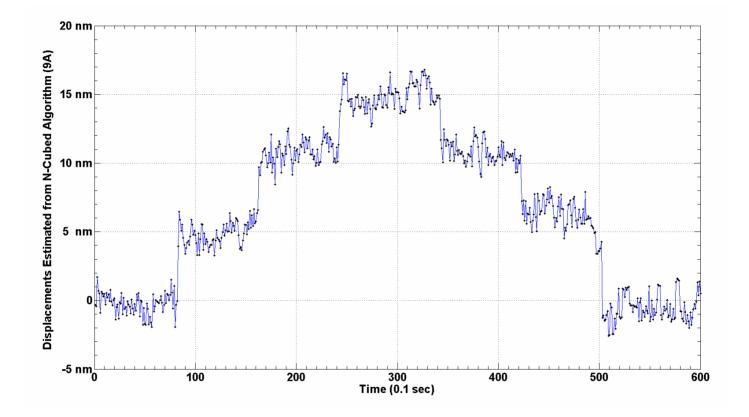
- Used in HP large format printers
- •Total cost of optics: \$60
- •1/50 pixel size displacement detection

J. Gao, C. Picciotto, E. Hoarau, W. Jackson and W. Wu NNT 2004 and Applied physics A in press Feb. 15, 2005



5 nm Displacement sensing using NDSE





J. Gao, C. Picciotto, E. Hoarau, W. Jackson and W. Wu NNT 2004 and Applied physics A in press



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Next Generation Nanoimprint Machine



Nanoimprint - s nm



300 Time (0.1 sec) 400

500

51

200

Summary



- HP is one of the earliest company/university to investigate NIL.
- QSR of HP labs is the first group made working circuit using NIL.
- Crossbar molecular memory with record density of 28 Gb/cm² (30 nm half pitch) were fabricated using NIL.
- NIL is capable of making real applications.
- Three generations of nanoimprinters were built by QSR.
- Fast and low-cost mold duplication process was developed to lower the cost of NIL further.
- Next generation nanoimprinter will integrate NIL and HP's precision imaging technology.



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Acknowledgement



- My colleagues and collaborators
- Supported in part by DARPA
- IEEE SF Bay Area Nanotechnology Council

You



